

IN THE CLAIMS

This listing of claims replaces all prior listings:

Claims 1-11 (Cancelled)

12. (Allowed) An electrical connection method for electrically connecting an electrical connection portion of a first object and an electrical connection portion of a second object, said method comprising the steps of:

providing an adhesive layer arrangement in which a first film-like adhesive layer composed of a plurality of conductive particles, a first binder containing said conductive particles, and a first filler is provided on the electrical connection portion of said first object and a second film-like adhesive layer composed of a second binder and a second filler is provided across a major surface of said first film-like adhesive layer;

heating and pressurization at a temperature and under a pressure at which said second film-like adhesive layer has a viscosity lower than that of said first film-like adhesive layer;

bringing together said electrical connection portions of said first and second objects sufficiently to cause said electrical connection portion of said second object to penetrate said second film-like adhesive layer for electrically connecting the electrical connection portion of said first object and the electrical connection portion of said second object by means of said conductive particles of said first film-like adhesive layer; and

heating said resultant arrangement at a temperature sufficient to cause said first and second film-like adhesive layers to cure into sufficiently hardened states.

13. (Allowed) The electrical connection method according to claim 12, wherein said step of heating and pressurizing comprises a first pressurization heating step for heating and pressurizing said first film-like adhesive layer and said second film-like adhesive layer in a temperature range of +/- 20 degrees C centered at a temperature at which the viscosity of said second film-like adhesive layer becomes the lowest and said step of heating said resultant arrangement comprises heating and pressurizing said first film-like adhesive layer and said second film-like adhesive layer at a temperature higher than reaction start temperature of said first film-like adhesive layer and said second film-like adhesive layer.

14. (Allowed) The electrical connection method according to claim 13, wherein, even in a temperature range of +/- 20 degrees C centered at a temperature at which the

viscosity of said second film-like adhesive layer becomes the lowest, the viscosity of said first film-like adhesive layer containing said conductive particles is higher than the viscosity of said second film-like adhesive layer, said second film-like adhesive layer is fluidized, said first film-like adhesive layer containing said conductive particles is not fluidized, and said conductive particles in said first film-like adhesive layer are made to exist between a wiring pattern on a circuit substrate and a protrusion electrode of an electrical component to electrically connect the wiring pattern and the protrusion electrode.

15. (Allowed) The electrical connection method according to claim 13, wherein the temperature at which the viscosity of said second film-like adhesive layer becomes the lowest is 80 degrees C.